

Title (en)
TEMPERATURE MANAGING FOR ELECTRONIC COMPONENTS

Title (de)
TEMPERATURVERWALTUNG FÜR ELEKTRONISCHE BAUTEILE

Title (fr)
GESTION DE TEMPÉRATURE DE COMPOSANTS ÉLECTRONIQUES

Publication
EP 2022302 A1 20090211 (EN)

Application
EP 06747851 A 20060602

Priority
SE 2006000657 W 20060602

Abstract (en)
[origin: WO2007142558A1] The invention provides a temperature managing arrangement (100, 200) comprising; a reservoir (240) arranged to accumulate a tempering liquid (242); a pressurizing device (210) arranged to pressurise the tempering liquid (242); at least one spray module (220) arranged to receive the pressurized liquid (242) and comprising at least one spraying device (222) arranged to spray the liquid (242) on at least one electronic component (224) so as to create a thermal coupling between the sprayed liquid (242) and the component (224); a heat remover (230) arranged to cool the tempering liquid (242), being in at least one of a liquid, a vapor or a mist form after spraying, when thermal energy is to be removed from said component (224); and wherein said tempering managing arrangement (200) is further comprising a heating device (245) arranged to heat the tempering liquid (242) before spraying when thermal energy is to be provided to said component (224). In addition, the invention provides a method for using said temperature managing arrangement.

IPC 8 full level
H05K 7/20 (2006.01); **H01L 23/473** (2006.01)

CPC (source: EP US)
H01L 23/345 (2013.01 - EP US); **H01L 23/427** (2013.01 - EP US); **H01L 23/4735** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US)

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA HR MK YU

DOCDB simple family (publication)
WO 2007142558 A1 20071213; AU 2006344160 A1 20071213; CN 101449637 A 20090603; EP 2022302 A1 20090211; EP 2022302 A4 20100721; JP 2009539246 A 20091112; MX 2008014702 A 20081201; US 2009283248 A1 20091119

DOCDB simple family (application)
SE 2006000657 W 20060602; AU 2006344160 A 20060602; CN 200680054805 A 20060602; EP 06747851 A 20060602; JP 2009513091 A 20060602; MX 2008014702 A 20060602; US 30261806 A 20060602